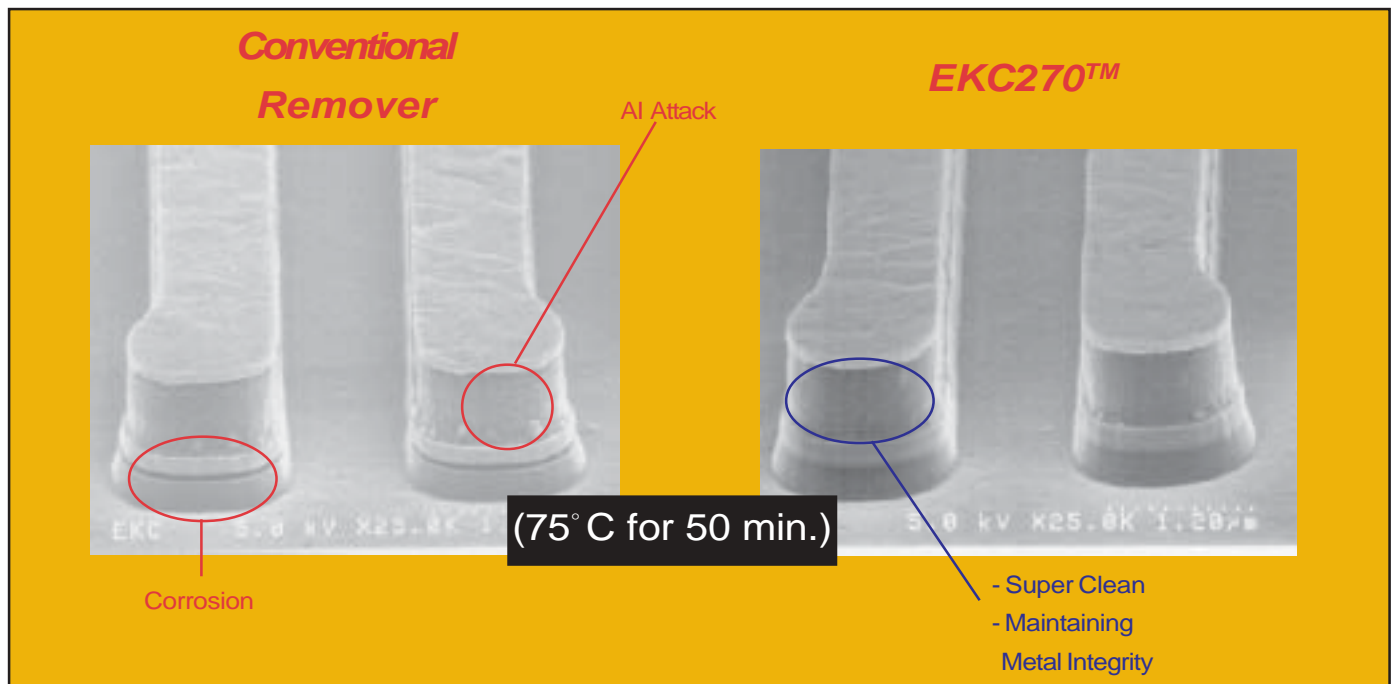


# EKC270™

EKC PlasmaSolv® Line - HDA™ Technology

## Benefits

- Formulated for optimum metal stack integrity
- Improves wide window process capability
- Enhanced post etch residue removal
- Patented & patent pending improved reduction chemistry
- ULSI grade specifications for advanced wafer cleaning
- Low evaporation rate at operating temperature



***EKC270™ Performs Beyond Standard Expectations...  
...even under aggressive processing conditions***

**[WWW.EKCTECH.COM](http://WWW.EKCTECH.COM)**

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**DuPont Electronic Technologies**

 *The miracles of science*

US Patents: 5334332,5482566,5672577,5902780,5911832,6000411,6110881,6140287  
Non-US Patents: Japan 2691952,3048207 Korea 150411 Taiwan NI-129295 Europe pending